





#### SURFACE MOUNT SWITCHING DIODE ARRAY

### **Features**

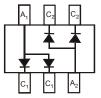
- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance
- Two "BAW56" Circuits In One Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standard for High Reliability

### **Mechanical Data**

- Case: SOT363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208 63
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)



Top View



Top View Internal Schematic

## Ordering Information (Note 4)

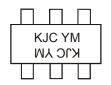
Part Number	Case	Packaging
BAW56DW-7-F	SOT363	3000/Tape & Reel
BAW56DWQ-7-F	SOT363	3000/Tape & Reel

**SOT363** 

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

## **Marking Information**



KJC = Product Type Marking Code YM = Date Code Marking Y = Year ex: N = 2002 M = Month ex: 9 = September

## Date Code Key

Year	2002	2003		2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018
Code	Ν	Р		V	W	Х	Υ	Z	Α	В	С	D	Е	F
Month	Jan	Fe	b N	/lar	Apr	May	Jun	Jul	Aug	Se	ep .	Oct	Nov	Dec
Code	1	2		3	4	5	6	7	8	9	9	0	N	D



# 

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		$V_{RM}$	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	75	٧
RMS Reverse Voltage		V <sub>R(RMS)</sub>	53	V
Forward Continuous Current	(Note 5)	I <sub>FM</sub>	300	mA
Average Rectified Output Current	(Note 5)	lo	150	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0µs @ t = 1.0s	I <sub>FSM</sub>	2.0 1.0	А

## **Thermal Characteristics**

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 5)	$P_{D}$	200	mW	
Thermal Resistance Junction to Ambient Air	(Note 5)	$R_{ hetaJA}$	625	°C/W	
Operating and Storage Temperature Range		$T_J,T_STG$	-65 to +150	°C	

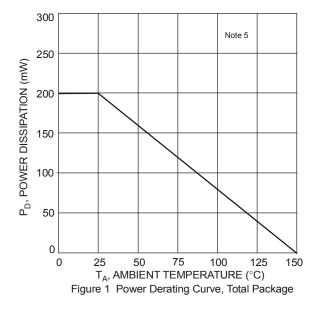
## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

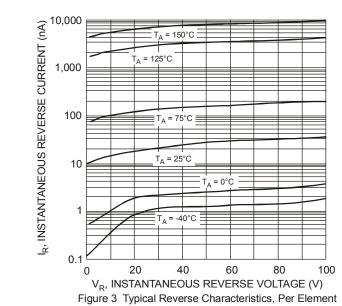
Characteristic		Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage	(Note 6)	$V_{(BR)R}$	75	_	V	$I_R = 2.5 \mu A$
Forward Voltage		V <sub>F</sub>	_	0.715 0.855 1.0 1.25	V	I <sub>F</sub> = 1.0mA I <sub>F</sub> = 10mA I <sub>F</sub> = 50mA I <sub>F</sub> = 150mA
Reverse Current	(Note 6)	I <sub>R</sub>	_	2.5 50 30 25	μΑ μΑ μΑ nA	V <sub>R</sub> = 75V V <sub>R</sub> = 75V, T <sub>J</sub> = +150°C V <sub>R</sub> = 25V, T <sub>J</sub> = +150°C V <sub>R</sub> = 20V
Total Capacitance		Ст	_	2.0	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time		t <sub>rr</sub>	_	4.0	ns	$I_F = I_R = 10 \text{mA},$ $I_{rr} = 0.1 \text{ x } I_R, R_L = 100 \Omega$

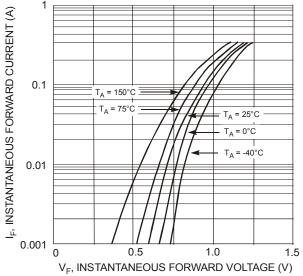
Notes:

<sup>5.</sup> Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf. 6. Short duration pulse test used to minimize self-heating effect.









V<sub>F</sub>, INSTANTANEOUS FORWARD VOLTAGE (V) Figure 2 Typical Forward Characteristics, Per Element

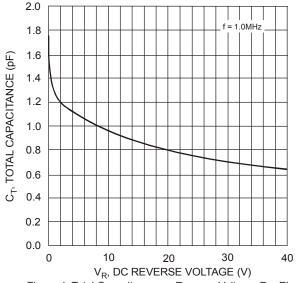
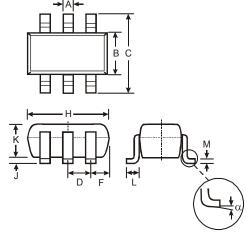


Figure 4 Total Capacitance vs. Reverse Voltage, Per Element

# **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



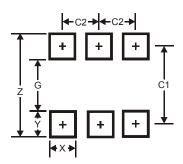
	SOT363							
Dim	Min Max Typ							
Α	0.10	0.30	0.25					
В	1.15	1.35	1.30					
C	2.00	2.20	2.10					
D	0.65 Typ							
F	0.40 0.45 0.42							
Н	1.80	2.20	2.15					
J	0	0.10	0.05					
K	0.90	1.00	1.00					
L	0.25	0.40	0.30					
M	0.10	0.22	0.11					
α	0°	8°	-					
All	All Dimensions in mm							

May 2013



## Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Υ	0.6
C1	1.9
C2	0.65

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